

# SOUTHEASTCON 2017 HARDWARE COMPETITION RULES

## *Episode MMXVII: The Engineering Force Awakens*

### Errata Document

The official rules document was frozen on October 10<sup>th</sup>. This document allows for slight changes or clarification to the official rules to be highlighted in a separate errata document.

Each errata item will be added to the list below, along with the last change per errata item:

➤ Stage 1 conductive pads (updated Nov 27, 2016)

The initial document described the probe pads as “six flag conductive copper pads”. The pads, as fabricated, are standard FR4 fiberglass (1.6 mm thick) with 0.35 mm copper pads with a HASL finish. HASL stands for hot air solder finish and the finish is applied by dipping the boards in molten solder and then hot air is used to blow off the excess solder from the surface. This will result in a finish that is smooth and will not tarnish like a bare copper pad. The pads are 0.7” in diameter to allow, at most, a 0.1” variation in placement of the 0.5” diameter holes in the plywood.